



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD70N10S3L-12		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000389812						
<b>Package</b>		PG-TO252-3-11		<b>Weight*</b>		373.28 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.755	1.54	1.54	15418	15418
leadframe	non noble metal	iron	7439-89-6	0.234	0.06		628	
	inorganic material	phosphorus	7723-14-0	0.070	0.02		188	
	non noble metal	copper	7440-50-8	234.187	62.76	62.84	627377	628193
wire	non noble metal	aluminium	7429-90-5	3.955	1.06	1.06	10596	10596
encapsulation	organic material	carbon black	1333-86-4	1.206	0.32		3230	
	plastics	epoxy resin	-	21.102	5.65		56531	
	inorganic material	silicondioxide	60676-86-0	98.275	26.33	32.30	263274	323035
leadfinish	non noble metal	tin	7440-31-5	3.740	1.00	1.00	10019	10019
plating	non noble metal	nickel	7440-02-0	0.091	0.02		243	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	244
solder	noble metal	silver	7440-22-4	0.117	0.03		312	
	non noble metal	tin	7440-31-5	0.093	0.02		250	
	non noble metal	lead	7439-92-1	4.454	1.19	1.24	11933	12495
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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